



VMDSEMI

VUSA003R600PA

Datasheet



VMDSEMI

General Description

Symbol

| $V_{(BR)DSS}$ | $R_{DS(ON)_{max}}$ | I_D |
|---------------|--------------------|-------|
| -30V | 60mΩ@-10V | -5.1A |
| | 67mΩ@-6V | |
| | 105mΩ@-4.5V | |

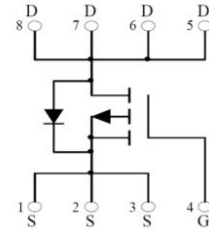


Figure 1 Symbol of VUSA003R600PA

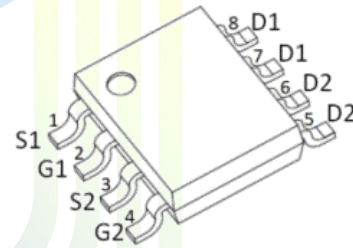
Features

- Trench FET Power MOSFET
- Excellent $R_{DS(on)}$ and Low Gate Charge

Application

- Load Switch for Portable Devices
- Battery Switch

Package Type



SOP8

Figure 2 Package Type of VUSA003R600PA

Ordering Information

| Product Name | Package |
|---------------|---------|
| VUSA003R600PA | SOP8 |

Absolute Maximum Ratings ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Rating | Unit |
|---|-----------|------------|------------------|
| Drain-Source Voltage | V_{DSS} | -30 | V |
| Gate-Source Voltage | V_{GSS} | ± 20 | V |
| Continuous Drain Current ^{Note1} | I_D | -5.1 | A |
| Pulsed Drain Current ^{Note2} | I_{DM} | -20 | |
| Single Pulsed Avalanche Energy ^{Note6} | E_{AS} | 20 | mJ |
| Total Power Dissipation ^{Note4} | P_D | 1.4 | W |
| Junction Temperature | T_J | 150 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | -55 to 150 | $^\circ\text{C}$ |

Thermal Resistance

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|-----------------|-----|-----|-----|---------------------------|
| Thermal Resistance, Junction-to-Ambient ^{Note5} | $R_{\theta JA}$ | | 89 | | $^\circ\text{C}/\text{W}$ |

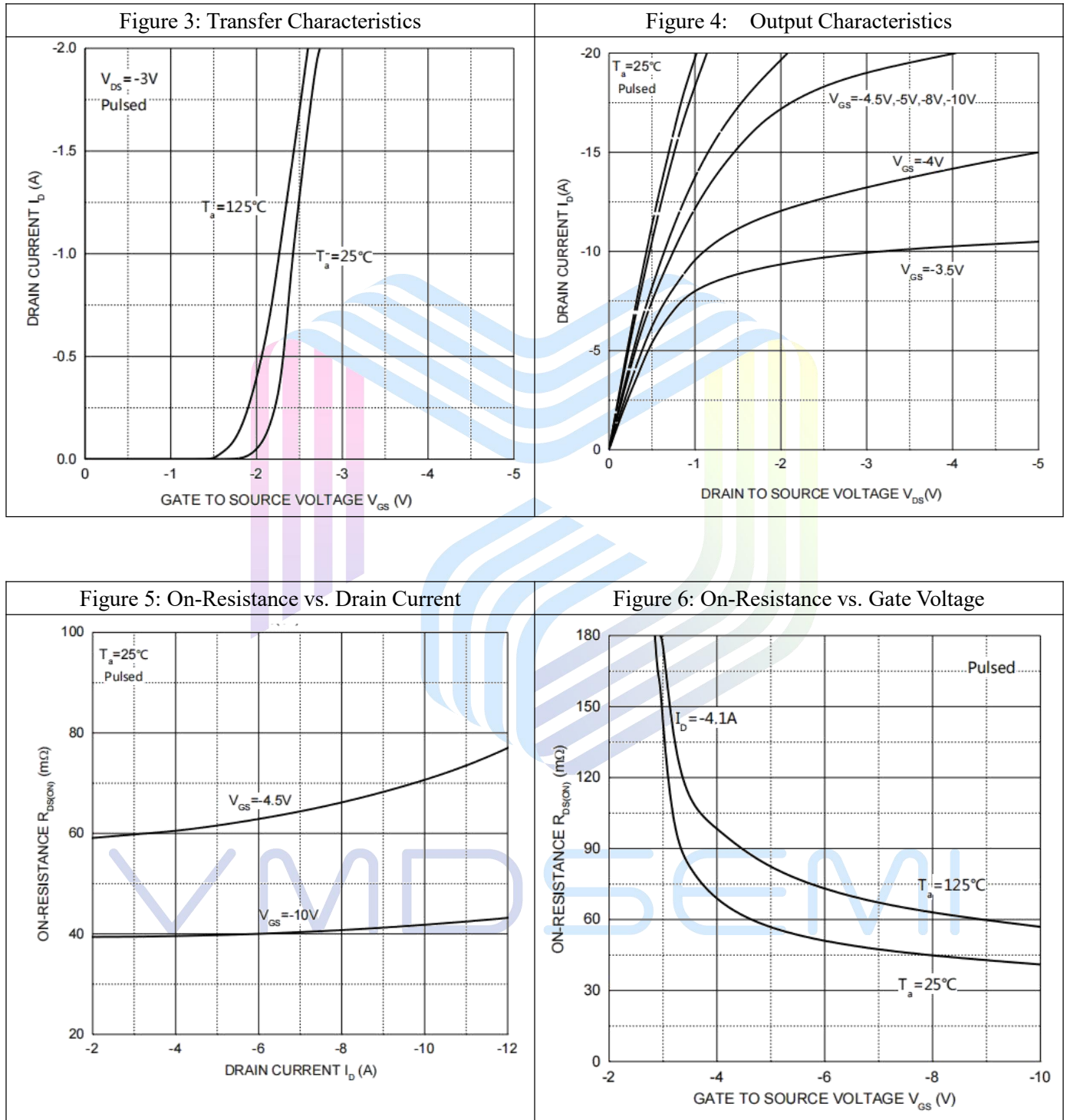
Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

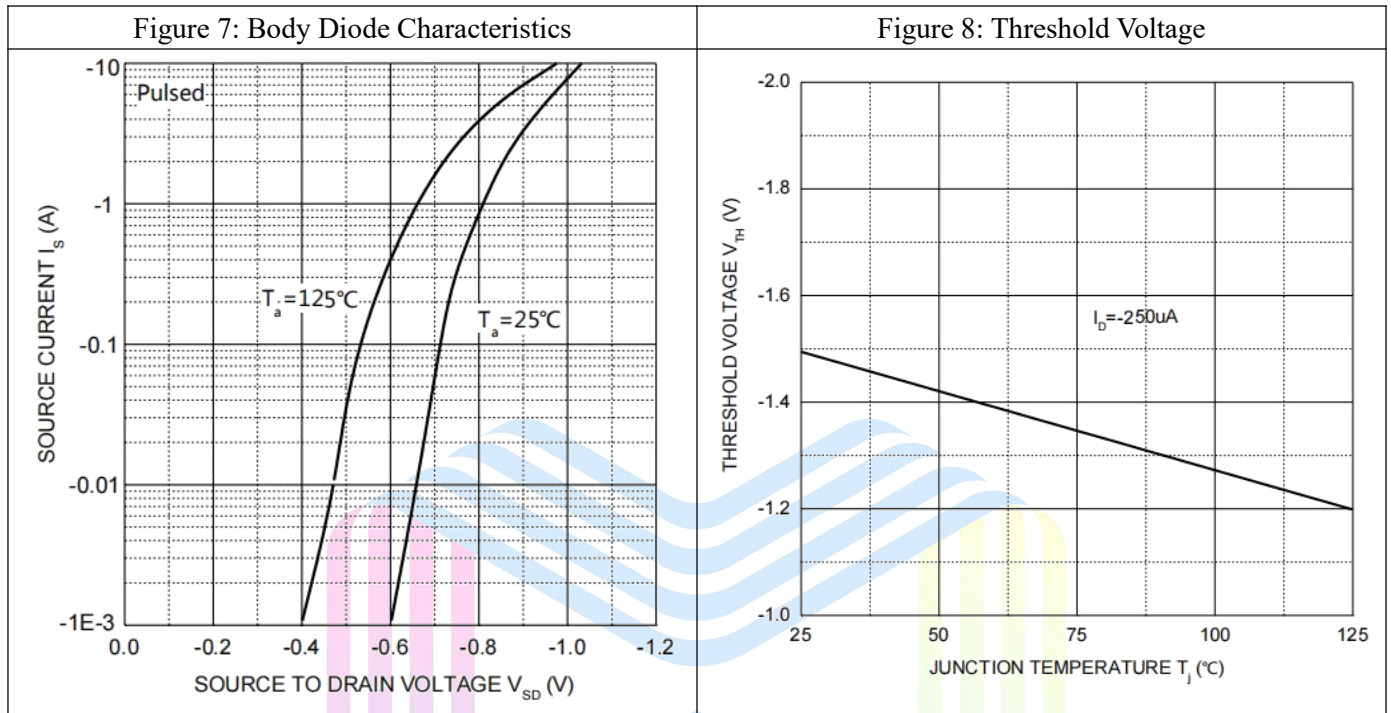
| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|--|--------------|--------------------------------|------|------|-----------|---------|
| Statistic Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | -30 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=-24V, V_{GS}=0V$ | | | -1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | | | ± 100 | nA |
| Gate Threshold Voltage ^{Note3} | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1.0 | -1.5 | -2.0 | V |
| Static Drain-Source On-Resistance ^{Note3} | $R_{DS(ON)}$ | $V_{GS}=-10V, I_D=-4.6A$ | | 42 | 60 | mΩ |
| | | $V_{GS}=-6V, I_D=-4.1A$ | | 51 | 67 | |
| | | $V_{GS}=-4.5V, I_D=-2A$ | | 62 | 105 | |
| Forward transconductance ^{Note3} | g_{FS} | $V_{DS}=-15V, I_D=-4.6A$ | 5 | | | S |
| Dynamic Characteristics | | | | | | |
| Total Gate Charge | Q_g | $V_{DS}=-15V$ | | | 40 | nC |
| Gate-Source Charge | Q_{gs} | $V_{GS}=-10V$ | | 4 | | |
| Gate-Drain Charge | Q_{gd} | $I_D=-4.6A$ | | 6.3 | | |
| Gate Resistance | R_g | $f=1MHz, \text{Open drain}$ | | 4.5 | | Ω |
| Switching Parameters | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=-15V$ | | | 30 | ns |
| Turn-on Rise Time | t_r | $V_{GS}=-10V$ | | | 60 | |
| Turn-off Delay Time | $t_{d(off)}$ | $I_D=-1A$ | | | 120 | |
| Turn-off Fall Time | t_f | $R_G=6\Omega, R_L=15\Omega$ | | | 100 | |
| Diode Characteristics | | | | | | |
| Diode Forward Voltage ^{Note3} | V_{SD} | $V_{GS}=0V, I_S=-2.6A$ | | | -1.2 | V |
| Diode Forward Current | I_S | | | | -5.1 | A |
| Pulsed Diode Forward Current | I_{SM} | | | | -20 | A |

Notes :

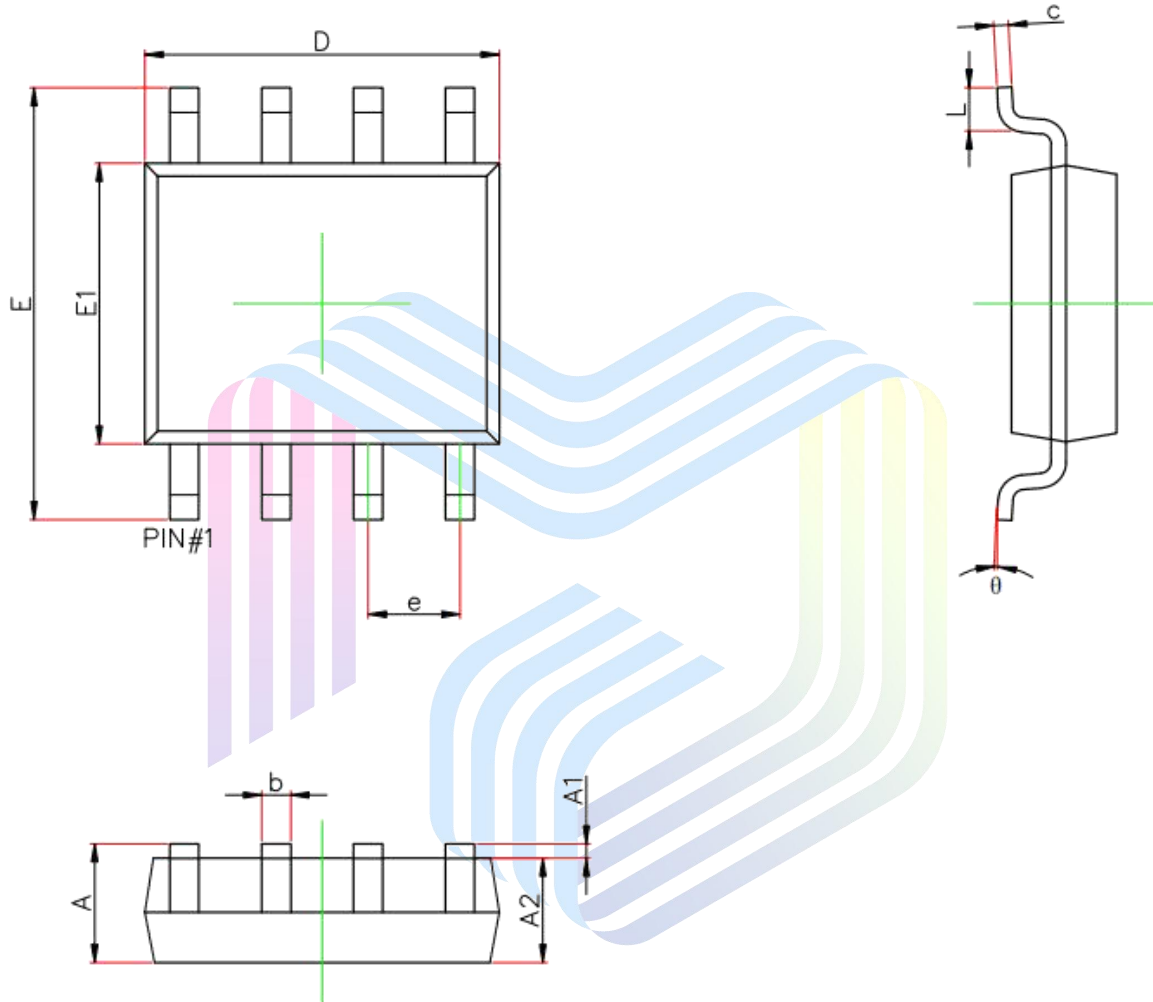
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 5.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.
- 6.EAS condition: $V_{DD}=-20V, L=0.5mH, R_G=25\Omega$, Starting $T_J = 25^\circ\text{C}$

Typical Performance Characteristics





VMDSEMI

Mechanical Dimensions:
SOP8 Package Information


| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.156 | 0.250 | 0.006 | 0.010 |
| D | 4.700 | 5.100 | 0.185 | 0.201 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| E | 5.800 | 6.200 | 0.228 | 0.244 |
| E1 | 3.700 | 4.100 | 0.146 | 0.161 |
| L | 0.400 | 1.270 | 0.016 | 0.05 |
| θ | 0° | 8° | 0° | 8° |

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